WIRE-TO-BOARD CONNECTOR CONTACTS





PRODUCT DRAWING



3D PDF

TE CONNECTIVITY (TE) 2.0mm, Crimp, Contact HPI | HDR

1735801-1

TE Internal Number: 1735801-1

Always EU RoHS/ELV Compliant

Contact Type Socket

Centerline 2 mm [.079 in]

Wire/Cable Size (AWG) 30 - 24

Wire/Cable Size (mm²) .05 - .02

Contact Mating Area Plating Material Tin



Product Drawings

2.0MM PITCH HPI CRIMP CONTACT

PDF English

CAD Files

3D PDF

PDF **3D**

Customer View Model

2D_DXF.ZIP English

Customer View Model

3D_IGS.ZIP English

Customer View Model

3D_STP.ZIP English

Product Specifications

Product Specification

Application Specification

HPI CONNECTOR, 2.0MM PITCH, LOCKING TYPE

AMP 2.0mm Pitch HPI Wire To Board System.

Product Environmental Compliance

TE Material Declaration

MD_1735801-1_05122014725_dmtec

PDF English

Please review product documents or contact us for the latest agency approval information. Please Note: Use the Product Drawing for all design activity.

Product Type Features	Connector System Wire/Cable Type Product Type Applies To	Wire/Cable Discrete Wire Contact Wire/Cable
Electrical Characteristics	Operating Voltage	250 VAC [250 VDC]
Contact Features	Contact Type Contact Mating Area Plating Material Contact Current Rating (A) Contact Base Material Contact Plating Material	Socket Tin 3 Phosphor Bronze Tin
Termination Features	Crimp Area Plating Thickness (μin) Crimp Area Plating Material	80 Pre-Tin
Housing Features	Centerline	2 mm [.079 in]
Dimensions	Wire/Cable Size (AWG) Wire/Cable Size (mm²)	30 – 24 .05 – .02
Usage Conditions	Operating Temperature Range	-25 – 105 °C [-13 – 221 °F]
Operation/Application	For Use With	1735447-x- 2041423-x
Packaging Features	Packaging Method Packaging Quantity	Reel 10000

